PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6038958

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|----------------|----------------|
| MITSUHIKO SANO | 01/20/2020 |

RECEIVING PARTY DATA

| Name: | TOSHIBA MITSUBISHI-ELECTRIC INDUSTRIAL SYSTEMS CORPORATION |
|-------------------|--|
| Street Address: | 3-1-1, KYOBASHI, |
| Internal Address: | CHUO-KU, |
| City: | TOKYO |
| State/Country: | JAPAN |
| Postal Code: | 104-0031 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 16652417 |

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 5713766333

Email: anaquadocketing@Xsensus.com

Correspondent Name: XSENSUS LLP

Address Line 1: 200 DAINGERFIELD ROAD

Address Line 2: SUITE 201

Address Line 4: ALEXANDRIA, VIRGINIA 22314

| ATTORNEY DOCKET NUMBER: | 14078US01 |
|-------------------------|--|
| NAME OF SUBMITTER: | TIERNEY FARRELL |
| SIGNATURE: | /Tierney Farrell/ |
| DATE SIGNED: | 03/31/2020 |
| | This document serves as an Oath/Declaration (37 CFR 1.63). |

Total Attachments: 1

source=14078US01_Assignment#page1.tif

PATENT REEL: 052266 FRAME: 0974

505992248

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

| Title of Invention | METHOD FOR CALCULATING PLATE THICKNESS SCHEDULE FOR TANDEM ROLLING MACHINE AND ROLLING PLANT | |
|--|---|--|
| As the below na | med inventor, I hereby declare that: | |
| This declaration | The attached application, or | |
| is directed to: | ☑ United States application or PCT international application number PCT/JP2019/042506 | |
| filed on Octobe | er 30, 2019 | |
| The above-ident | ified application was made or authorized to be made by me. | |
| I believe that I as WHEREAS, | m the original inventor or an original joint inventor of a claimed invention in the application. TOSHIBA MITSUBISHI-ELECTRIC INDUSTRIAL SYSTEMS CORPORATION | |
| | rred to as "ASSIGNEE") having places of business at: 3-1-1, Kyobashi, Chuo-ku, | |
| Tokyo 104-003 | 1 JAPAN | |
| is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries; | | |
| the United States the terms of the l application) and the United States | EFORE, for good, valuable, and adequate consideration, the receipt of which is hereby acknowledged, I, is do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in a sand its territorial possessions and in all foreign countries (including the right to claim priority under international Convention and other relevant International Treaties and Arrangements from the aforesaid the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in a and its territorial possessions and in any and all foreign countries and in and to any and all divisions, ations, substitutions and renewals thereof. | |
| my entire right, t assigns, to the fu | orize and request the Patent Office Officials in the United States and its territorial possessions and any puntries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of itle and interest in and to the same, for the sole use and behoof of said ASSIGNEE, its successors and ll end of the term for which said Letters Patent may be granted, as fully and entirely as the same would y me had this Assignment and sale not been made. | |
| Further, I agree that I will communicate to said ASSIGNEE or its representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries. | | |
| I hereby acknowledge or imprisonn | owledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by nent of not more than five (5) years, or both. | |
| LEGAL NAME | OF INVENTOR | |
| Inventor: Mitsu | Date. January 20, 2020 | |
| Signature: | Mitsuhika Sano | |
| XSENSUS LLP | | |

XSENSUS LLP ATTORNEYS AT LAW 200 DAINGERFIELD ROAD, SUITE 201 Alexandria, VA 22314

> PATENT REEL: 052266 FRAME: 0975

RECORDED: 03/31/2020